Goddard Space Flight Center Colloquium Presentation April 30, 2002

Space-Relevant S&T Programs at Sandia National Laboratories

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& Chief Technology Officer
Sandia National Laboratories

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Sandia National Laboratories, a DOE National Laboratory, is located at six major sites



Tonopah Test Range,
Nevada

WIPP, New Mexico

Albuquerque, New Mexico



Kauai Test Facility, Hawaii



Livermore, California





Sandia — in round numbers

- 7,600 full-time employees
 - ~6,600 in New Mexico
 - ~1,000 in California
 - 600 buildings, 5M square feet
 - 1,400 Ph.D.'s, 1,700 Masters
 - 55% engineering
 - 33% science and mathematics
 - 12% computing and other
- Annual budget \$1.8B (FY02)







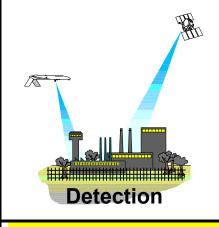
Sandia is a National Security Laboratory

Nuclear Weapons

Safe, Secure, **Reliable Weapons**



Nonproliferation & Materials Control





Surveillance

Energy & Critical Infrastructures



Energy



Information



Transportation

Emerging Threats





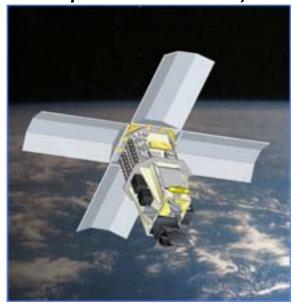


Architectural Surety



Remote detection and characterization of terrestrial features and activities is a key Sandia mission

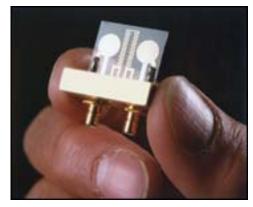
MTI (Multispectral Thermal Imager Experimental Satellite)



Facility Detection and Characterization

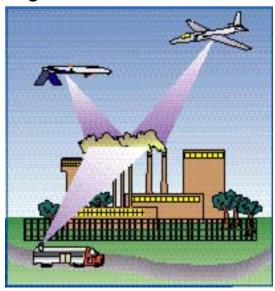


Chemical Microsensor



On-site Effluent Detection and Characterization

CALIOPE (Chemical Analysis by Laser Interrogation of Proliferant Effluents)



Remote Effluent Detection and Characterization



Sandia's Science and Technology Strategic Management Unit

Strategic Objective:

We will pursue

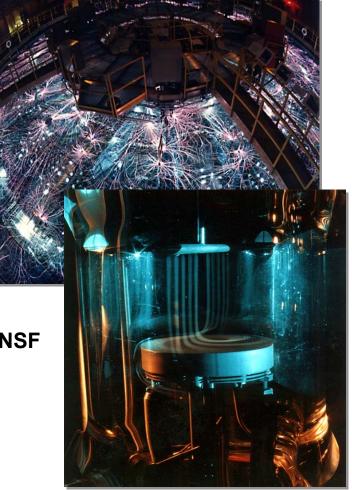
"science with the mission in mind" thereby providing solutions and options for the customers of Sandia's current and future business units.

Executive Leadership: Al Romig

Internal Customers: Lab Director and SBUs

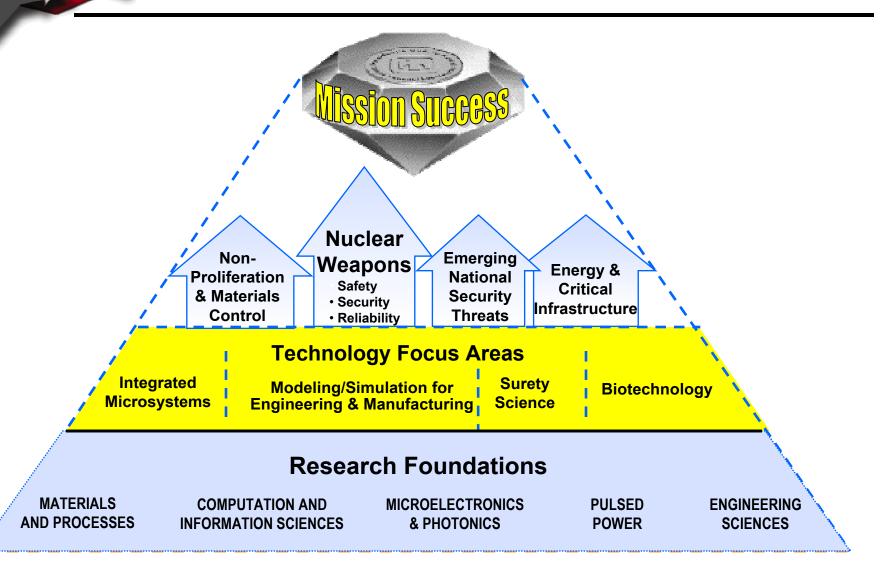
Primary External Customers: Industry, NASA, DOC, NIH, NSF

	<u>External</u>	<u>Internal</u>
FY01 Revenue/Costs	\$47M	\$330M
Direct SNL Labor:	123 FTEs	900 FTEs





Research and Technology Our most direct link to our missions

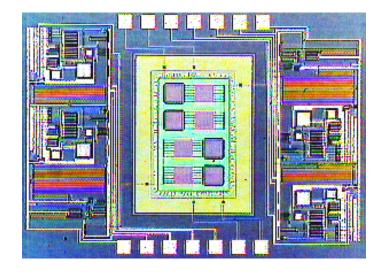




Electronics for the 21st Century:

Inventing the Future, and Making it Happen

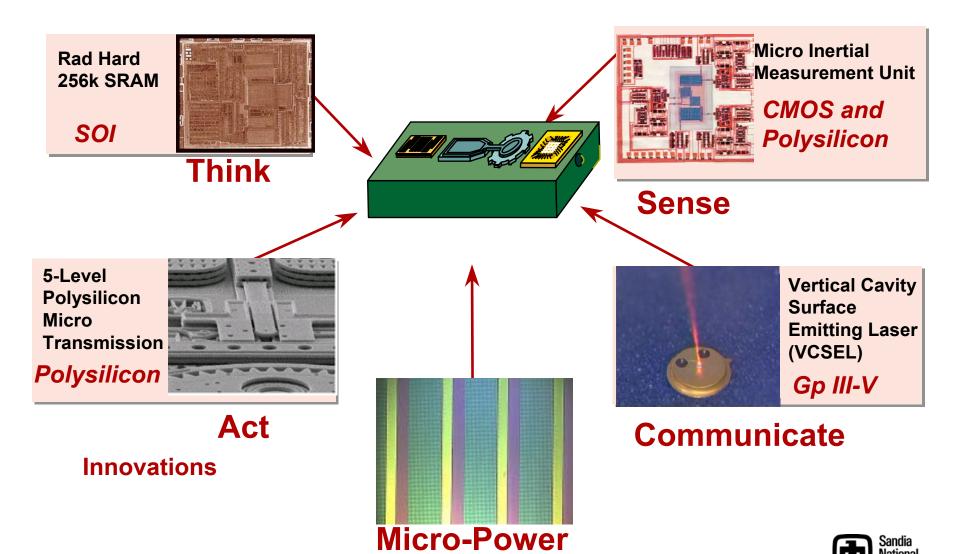
- The <u>next leap</u> in function of Integrated Circuits will involve more than just packing more transistors on the chip
- It will involve the building of new microscopic structures along side the transistors, giving the chip the ability to
 - Sense,
 - •Think
 - •Act
 - Communicate



This technology will impact our lives in this century as profoundly as the IC did in the last.

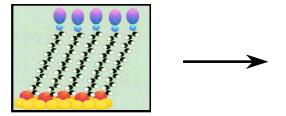


Microsystems provide new dimensions of functionality "transforming" Microelectronics into Microsystems



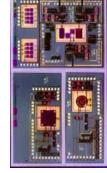
Technology Focus Area: Integrated Microsystems



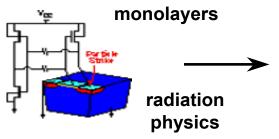


self-assembled

smart sensors



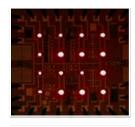
Think

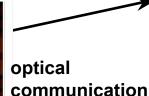


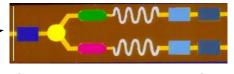
custom µprocessor

Micro-navigator



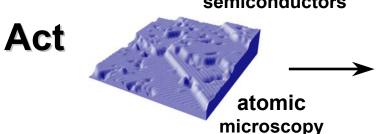


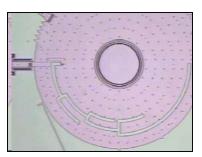


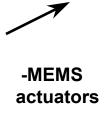


Chem Lab-on-a-Chip





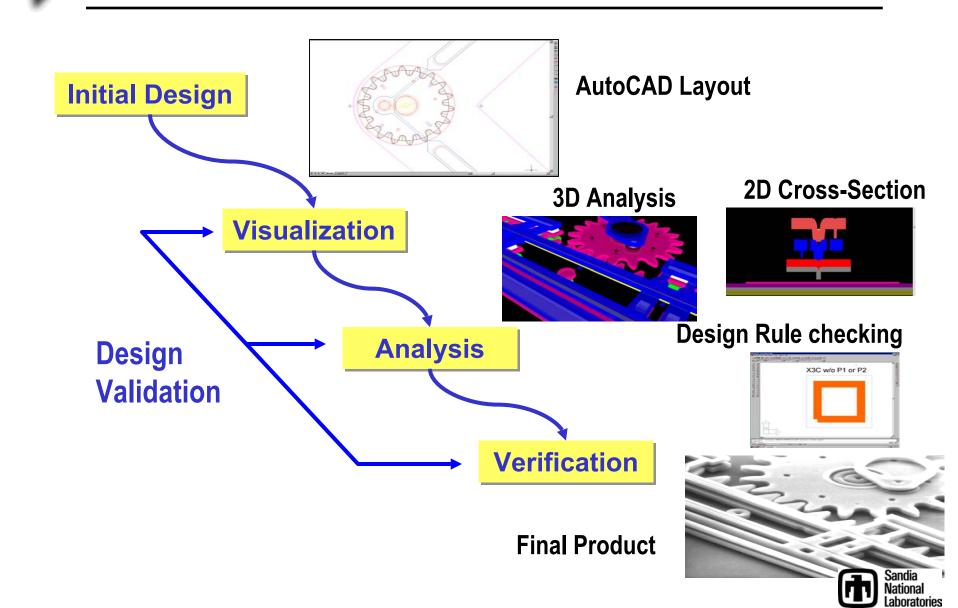




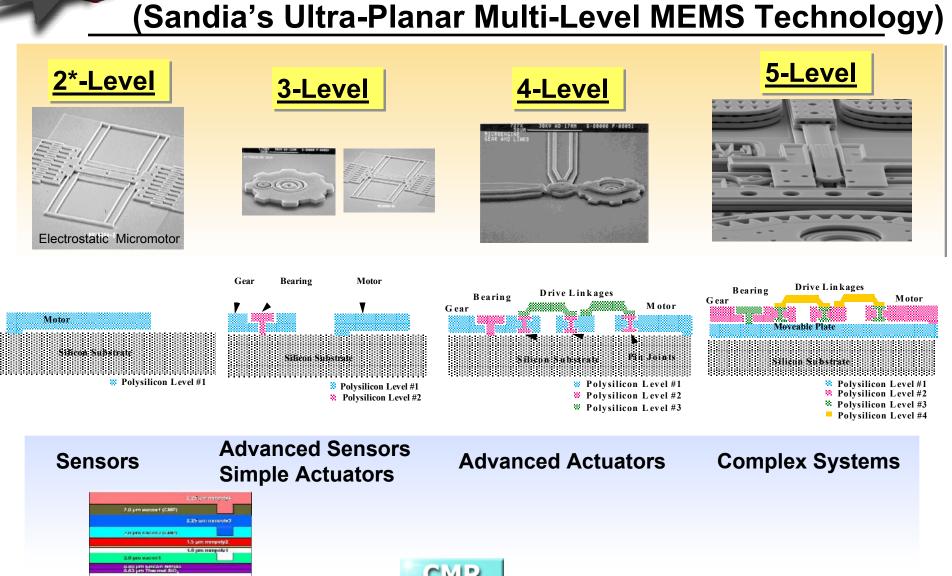


Sandia National Laboratories

MEMS Design - Process flow



SUMMITTM

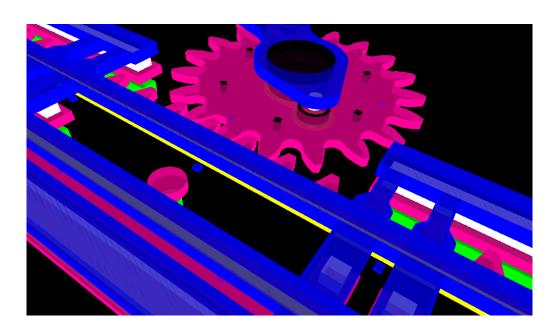


Substrate 6 Inch wafer, <100>, n-type-



Critical Microsystem Design Realization Needs

Process-Based 3-D Visualization



Accurate process model resulting in physically correct shapes

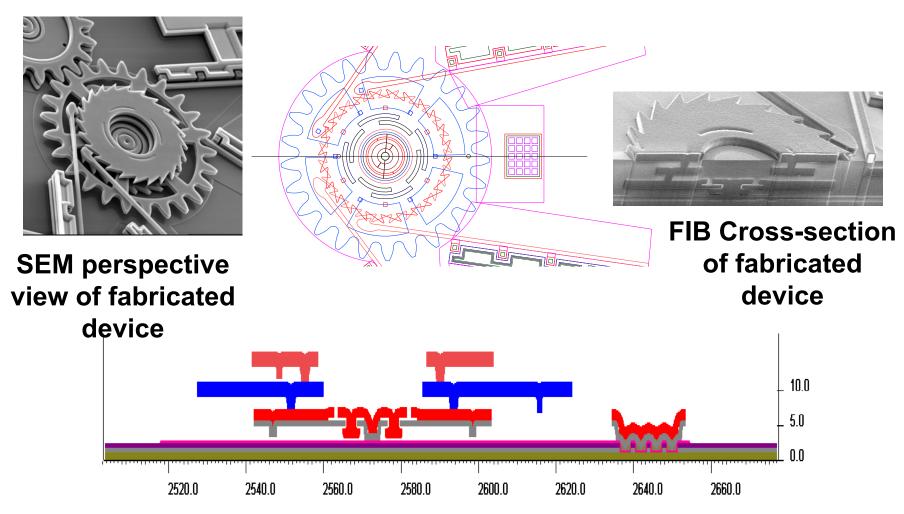
Integrated with layout tools

"Designer-Friendly" navigation interface





SUMMiT™ Process Cross-sections: Released Structure (Double Ratchet)





RF MEMS

Integration for performance, size and cost



Conformal Phased-Array Antennas

Wing

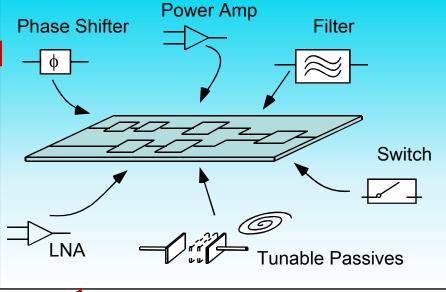




Fusible Radar for Weapons











- Micro-implantable Systems
- ·UAV's
- Portable ground based communications



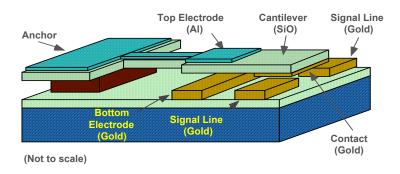




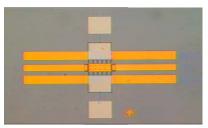


RF MEMS Technology

GaAs post-processing



Switch Diagram



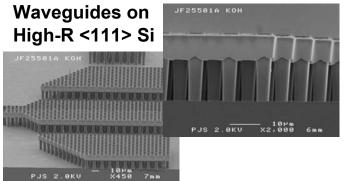
Switch & Waveguide



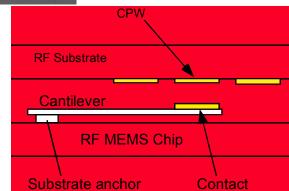
Switch

- Increased Integration of MMIC's
- Low temp. processing

High-Resistivity Si Processing



Flip chip bonding

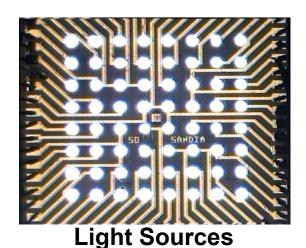


Advanced Concepts

- GaAs micromachining
- Bulk material processing



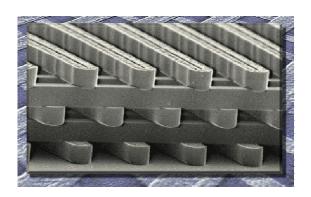
SNL's Principal Photonic Communication Building Blocks



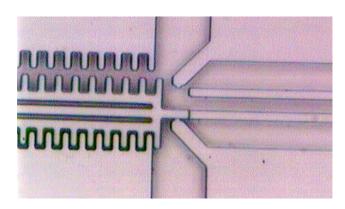
SESD4laser refletch mechB

Optical Receivers

Sandia



Waveguides

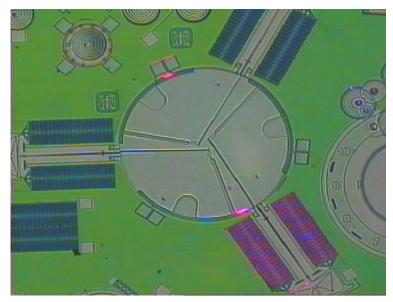


Optical Switches

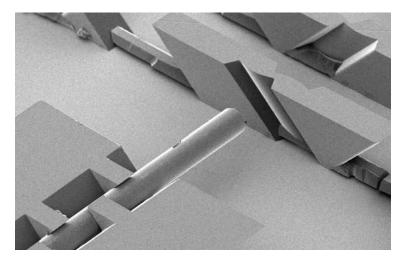


Optical MEMS

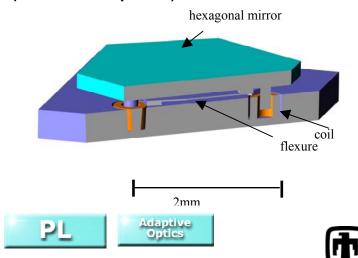
Free-space optical switching is currently one of the hottest applications of MEMS.



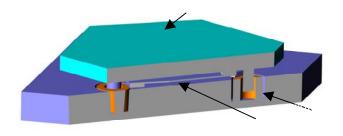




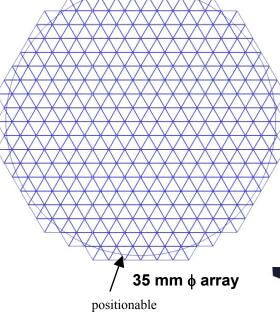
Single fiber with two optics in background. (PMMA: Clear plastic)



Adaptive Optics



2mm



Wavefront Correction

Changing Phase of Wavefront by increasing the path length

Correcting Atmospheric Turbulence

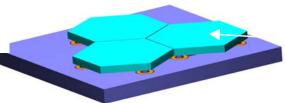
(Astronomy-twinkling)

Focusing the unfocused



Deformable thin film mirror (one surface)

- Combines bulk micromachining and surface micromachining
- laser based communications
- biomedical imaging
- laser welding
- terrestrial imaging



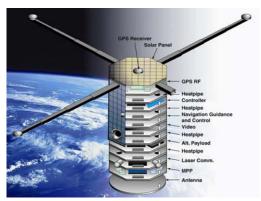
Segmented Mirrors

Tip and tilt and vertical movement

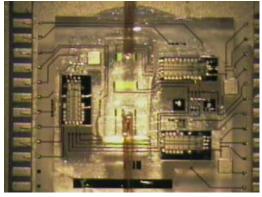


Micro-Power Sources:

The Microsystem Revolution requires advances in micro-power source technologies

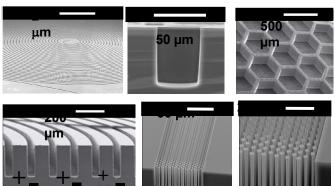






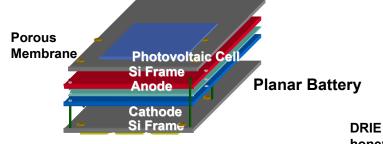
Nano-Satellites

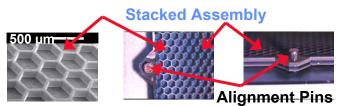
Positive Negative Well Silicon Well or Assembly



Micro-Robots

Chemical and Biological Sensors





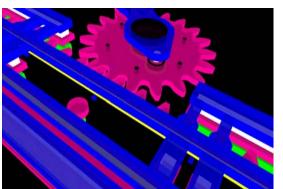
honeycomb well assembly for containment of positive and negative electroactive materials.

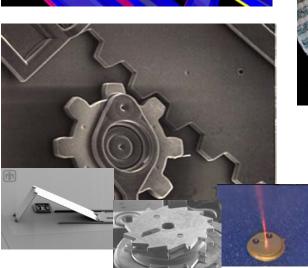


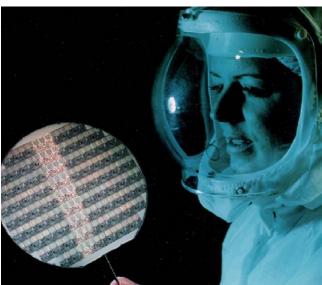




Microsystems and Engineering Sciences Applications

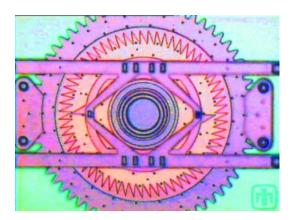




















MESA's scope was determined in the context of a <u>system</u> solution

The Nation's Brightest Scientists and Engineers

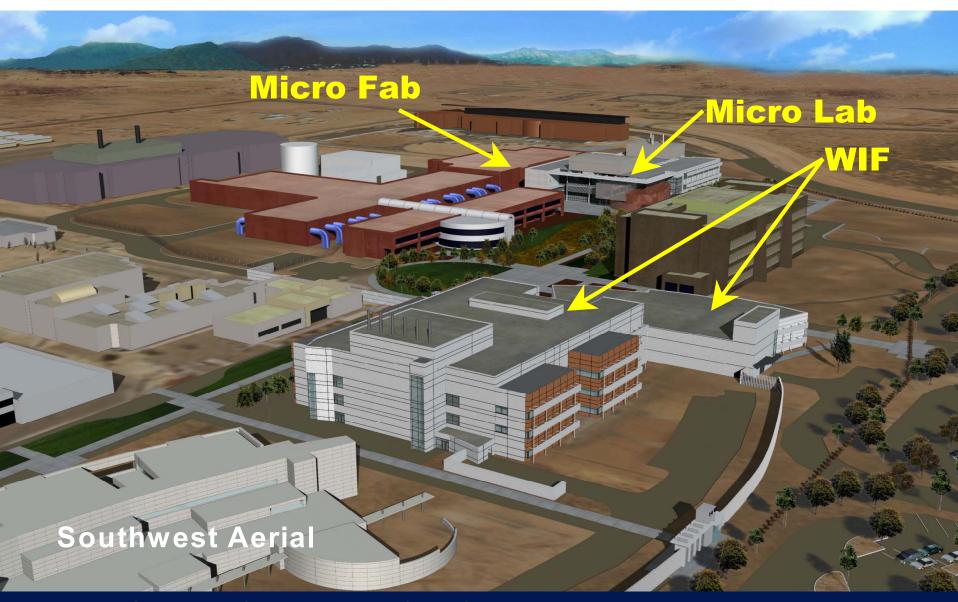
Using the Most Advanced Design and Simulation Tools

And The Most Advanced Microsystem Technologies

To Positively Impact
National Security
Now and in the Future

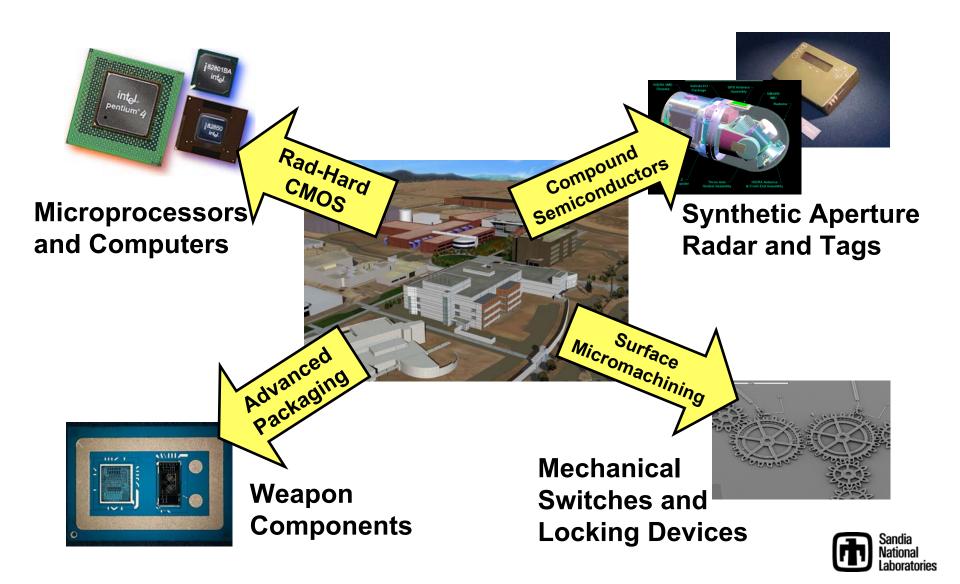


Southwest Aerial View of the MESA Complex

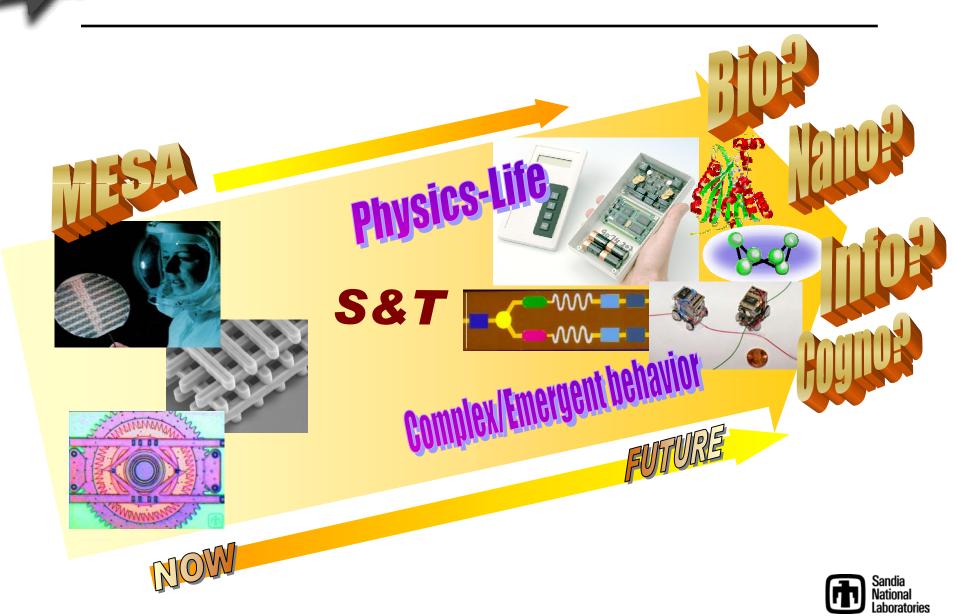


MESA is the Cornerstone of the Strategy to Meet our Mission Needs

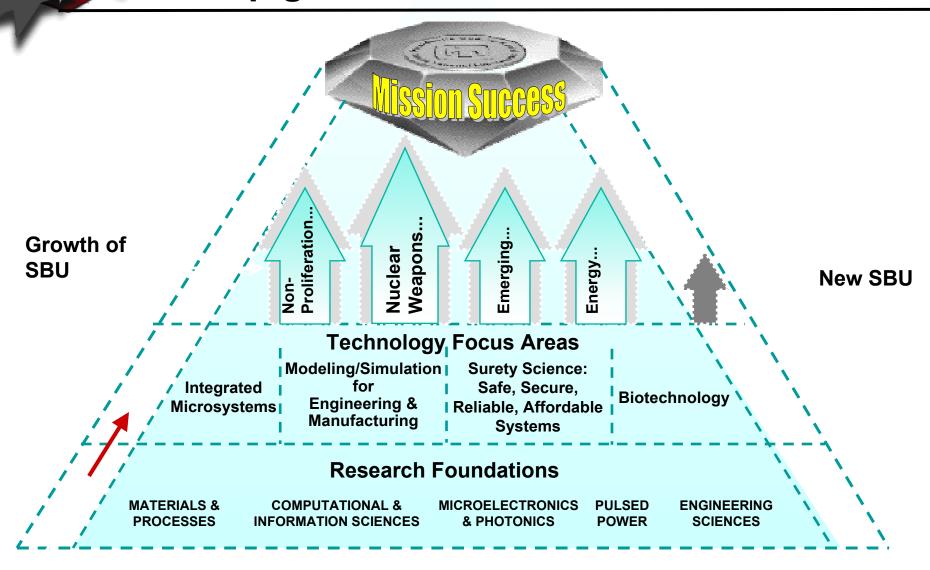
Microsystems technologies are advanced through flagship products



Impact of S&T - Today and Tomorrow



New (to Sandia) science will help grow current and new SBUs



Center for Integrated Nanotechnologies (CINT)



Officially...

Highly collaborative
 DOE National Facility

Focused on nanoscience and its integration across scientific disciplines and multiple length scales.

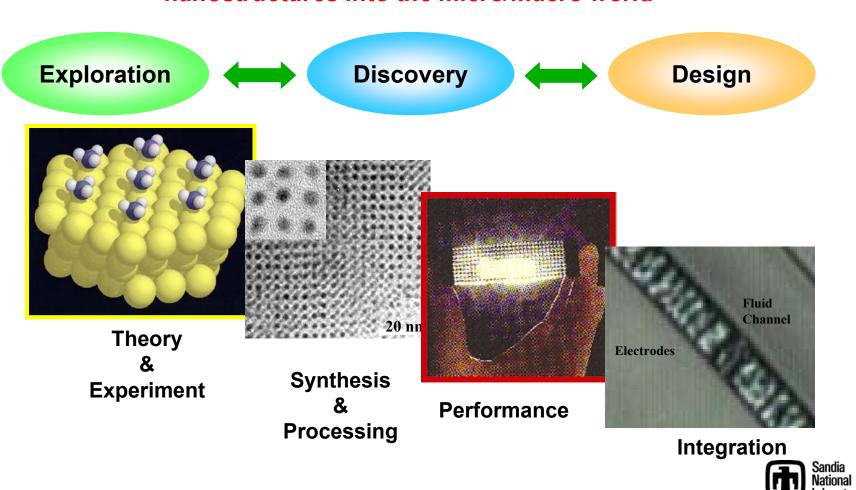
The Fact is... CINT will be what you make of it!



Vision

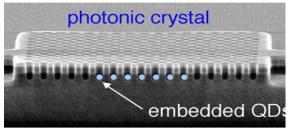
The Center for Integrated Nanotechnologies

Exploring the path from scientific discovery to the integration of nanostructures into the micro/macro world



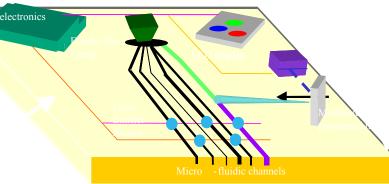
New nanoscience discoveries will have impact via micro and macro scales

Nanophotonics/Nanoelectronics

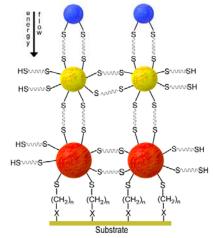








Complex Functional



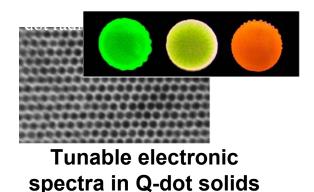
Nanomechanics

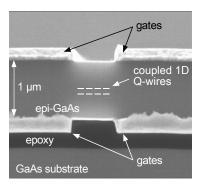


CINT's scientific thrusts capitalize on the expertise and capabilities of Los Alamos and Sandia

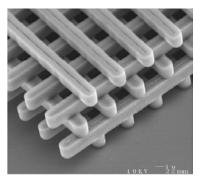


Nanoelectronics & Nanophotonics: Precise control of electronic and photonic wavefunctions to invoke novel and unique properties





Correlated states in coupled Q-wires

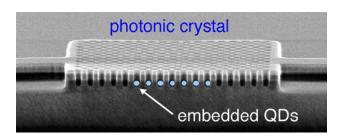


Tunable photon states in photonic structures

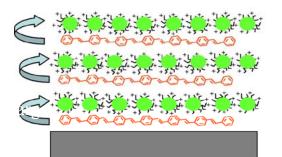
CINT Focus: New Phenomena



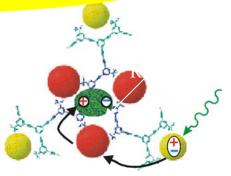
New Nanoscale Materials



Interplay between tunable electronic and photonic spectra



Organic/inorganic hybrid structures

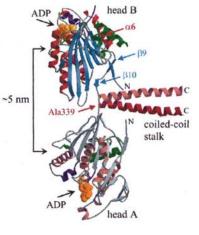


Bio-inspired photonic structures

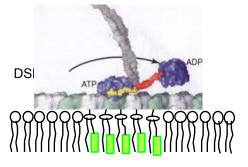


Nano-Bio-Micro Interfaces: Biological principles and functions imported into artificial bio-mimetic nano-and microsystems

motor proteins



biomimetic interfaces



Aggregated receptors

self-assembly

1-10 nm

molecular biology

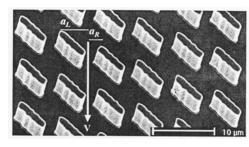
genetic

engineering

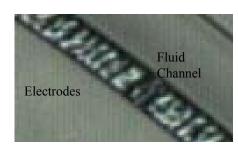
10 -100 nm

complexation chemistry molecular modeling

fiber guides and activation systems



microfluidics



solid state physics microfabrication nanomechanics

10²-10⁴ nm

10⁵-10⁶ nm

fluid mechanics micromechanics biochemistry

CINT promotes the development of tailored nanomaterials and the scientific infrastructure required to integrate such materials into functional systems.



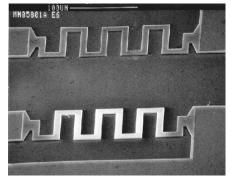
A critical success factor for Sandia: developing <u>Strategic</u> Partners



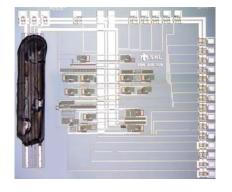


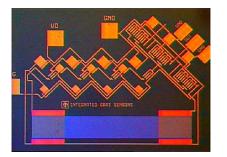


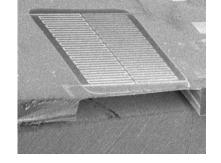
Industry partners provide significant S&T challenges

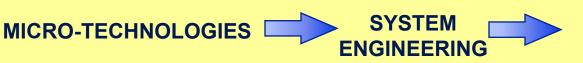












MICRO-ANALYTICAL SYSTEMS for GE & SNL APPLICATIONS





Our strategy for university partnerships...

- Focus on a few key campuses
- Build a relationship between our leaders (Campus Executives)
- Understand the nature of our ongoing efforts
- Identify focus R&D areas: seed with internal funding
- Expand and focus our faculty/students/employee programs
- Establish fast-track contracting (As-Ordered Agreement)
- Jointly pursue new opportunities
- Tie R&D to recruiting









NASA and Sandia Work in Related Technology Arenas to Fulfill Our Respective Missions

Surety



- Risk Assessment
- Predictive Reliability
- Refurbishment
- State-of-Health Systems
- Advanced Materials
- Smart Structures

On-Orbit Capability



- Remote Sensing
- Nano/micro satellites
- Rad Hard Electronics
- On-orbit Computing
- Human State-of-Health
- Telemedicine

Power / Energy



- Combustion Research
- Nuclear Energy
- Advanced Sensors

Information Technology



- Advanced Computing
- Distributed Computing
- Modeling & Simulation

Kennedy

Johnson

Glenn

Sandia

Marshall

Goddard

JPL

Ames



Backup Foils

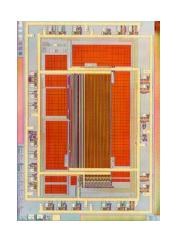


NASA / Sandia Cooperative Activities Have Been Win-Wins

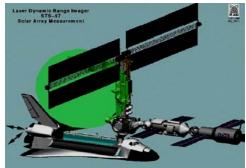


Mars
Pathfinder
Air Bag
Technology
(w/ JPL)

Radiation
Hardened
Pentium
(w/Goddard
and JPL)



Laser Dynamic Range Imager (w/JSC)





Int'l. Space Station Crew Return Vehicle (parafoils) (w/ JSC)



Thermal Protection System (w/Ames)

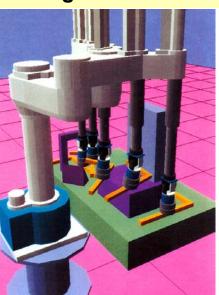
Aircraft Safety and Combustion Research (w/Glenn)

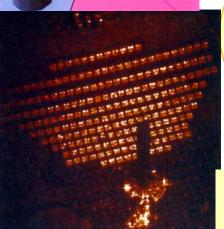


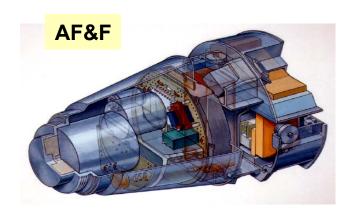


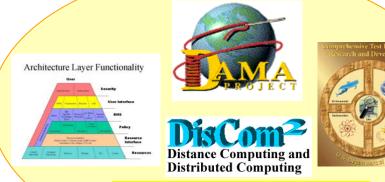
computational and Information Sciences support a wide range of applications

Intelligent machines









Information Systems

Image processing

Large scale, massively parallel computing resource





Identified Areas of Mutual Interest (NASA/SNL)

◆ Radiation Hardened Electronics (e.g. Pentium)

JSC, JPL, Goddard, Langley, Glenn

◆ Design Paradigm/Revolution in Engineering & Manufacturing JPL, Ames

♦ Neural Nets and 3 DANN Cube

JPL

♦ Sensors, Microsensors, Systemson-a-chip (SOAC) MEMS, In-situ Measurement JPL, JSC

♦ Nanostats/Microsat Technology

JPL, JSC

♦ High Integrity Software

Ames, JPL

♦ Robotics

JSC, Ames

◆ Data Compression for High Frequency Space Communication Glenn, JPL



Identified Areas of Mutual Interest (continued)

♦ Virtual Reality/Artificial Intelligence	JSC, JPL
◆ Advanced Manufacturing, Rapid Prototyping	JSC
♦ Sub-surface Explorer, Penetrator	JPL, JSC
♦ Micro-Navigational Aids (MEMS-based IMU's	JPL, JSC
♦ VCSELs, Non-volatile memories, mixed mode ASICs	JPL, Glenn
♦ ChemLab-on-a-Chip, Environmental Sensors	JSC, JPL
♦ Proximity Sensors, Collision Avoidance	JSC, JPL

Sensors, Robotics



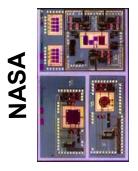
Win-Win Partnerships Model



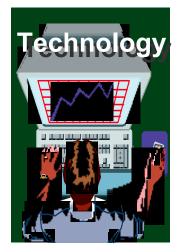












Collaboration to do B faster, better, cheaper for each partner



DOE Mission Application





NASA **Application**



- MEMS / Systems-on-achip / MicroNavigators
- Improved (Ceramic) Re-entry Tip Design / **Penetrator Technology**
- Rad-Hard High Rel ICs
- Scannerless Terrain **Mapper Technology**
- High Integrity/ **Reliability Software**
- Intelligent Systems / **Robotics / Space Electric Power**



Sandia's Nuclear Weapon components and subsystems will benefit from the availability of microtechnologies

"Weaponization" - - Design, engineering, testing, integration, and production interface for non-nuclear components



W88/MK5 Arming, Fuzing, and

Firing System

Total parts > 3000

Components/Subsystems

Neutron Generators
Arming/Safing System
Fuzing System
Firing System
Use Control System
Gas Transfer System
Power Supplies
Energetic Components
Electronics (Digital/Analog)
Structures & Packaging
Parachutes
Use Control Equipment
Test & Handling Equipment

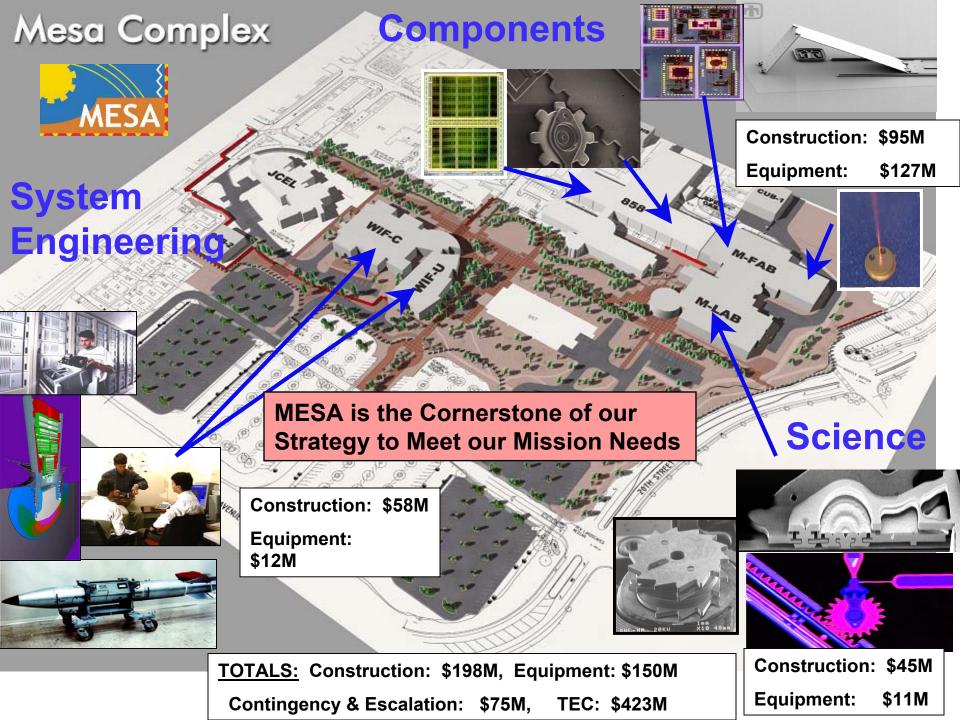
All parts must come together to form a high-rel system



B83 Strategic Bomb Total parts - 6,519

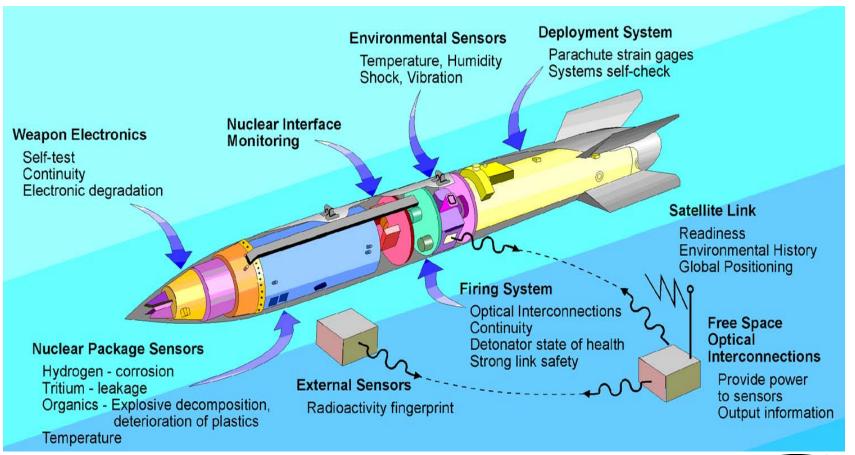
- Sandia developed 3,922
- Sandia specified 2,378





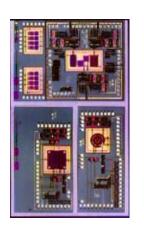
Sandia's Science-Based NW Product

Weapons that are inherently safe, know where they are at all times, diagnose and communicate their state of health and location, are tamper proof, cannot be armed until they have located their target, will not detonate until they have received and verified the fire command, and are reliable without underground testing





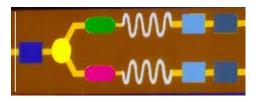
Three Integrated Microsystems are Under Development



Micronavigator

A collaboration with UC Berkeley)

Weapon guidance, weapon fuzing, commercial applications: e.g. air bags



Chem Lab-on-a-Chip

Weapon state-of-health, non-proliferation, counter-terrorism

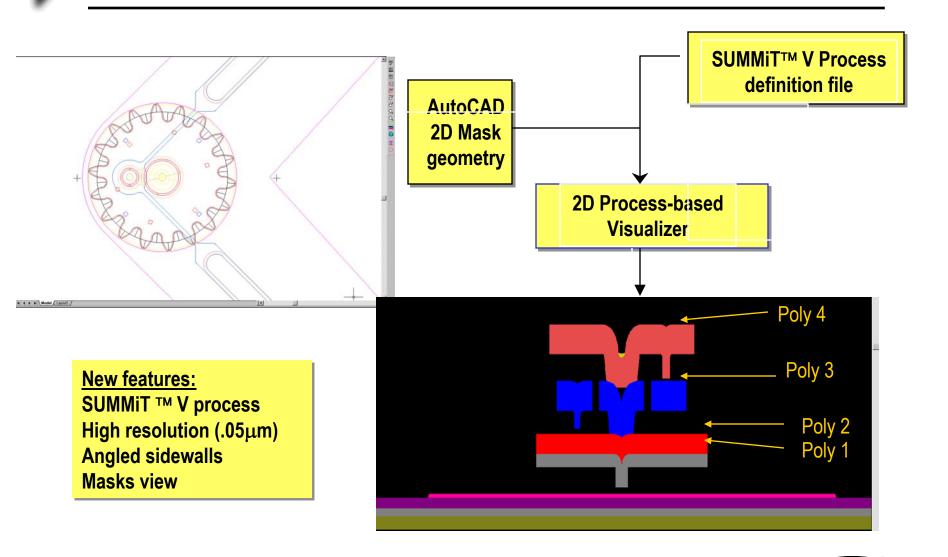


Micro-surety Device

Weapon surety, protection of high value assets

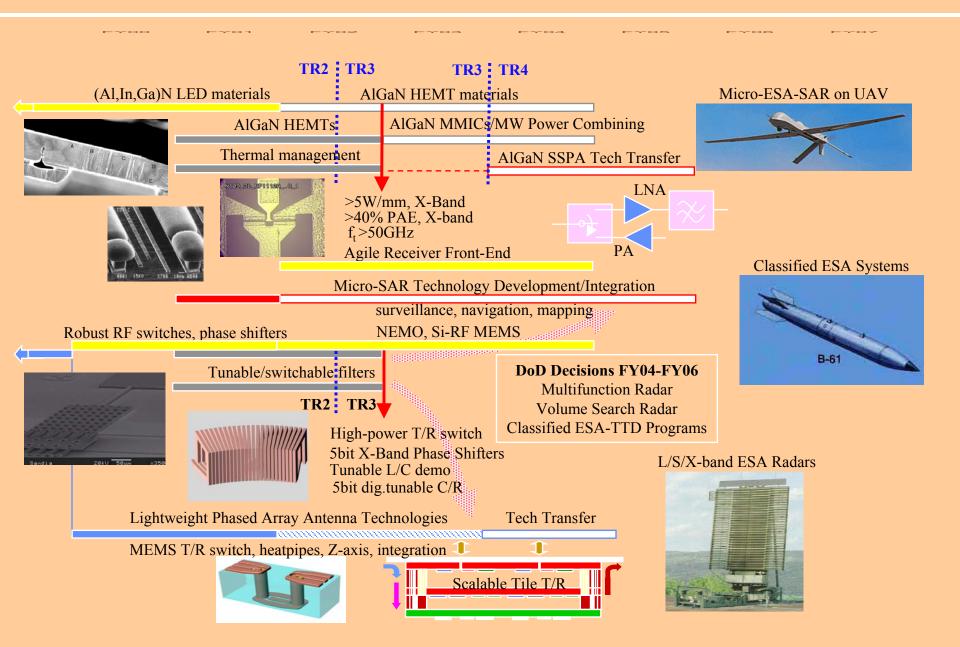


2D Process Visualizer - process flow





RF Microsystems Technologies Roadmap: Micro-SAR Technologies



RF Microsystems Technologies Roadmap: Photonics Communications

SAR Stabilization, non-GPS GN&C AlGaAs Active/Passive PICs RM/FOG PIC: Monolithic Integrated DFB LD/PM/PD W87 JTA Optoelectronic Heterointegration SiGe Photonics Integration High Efficiency Active/Passive Micro-Laser Research Classified Cryptologic 100GHz ESQW-SSEED Switching Research **Prototype Systems** Secure **Public Comm** Secure Communications Initiative 1300nm MW-MOD Polymeric SST **Systems** Radar/Tag Microwave Photonics High Current 1300/1550nm InP Balanced MW Classified ESA Systems 40Gbps WG Modulators 1550nm OADMs: SiON/Si, GaAs, InP Optical MM/WG Switches for TTD BFNs, Classified BFN Prototype GaAs A/P MOEMS Optical Backplane Switch F22 Optical Avionics **Dispersive Photonics** 650-1100nm VCSELs Robust 10Gbps 850nmVCSELs Low-power RF VCSEL FPA Interconnect, Insertion 1550nm/Tunable InP VCSELs 1300nm GaAs VCSELs Low-bandgap Optical Emitters

RF Microsystems Technologies Roadmap: Compound Semiconductor Microelectronics

